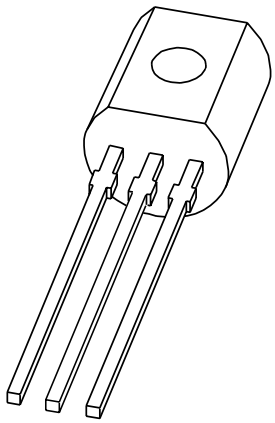
DATA SHEET



PBSS4350SA
50 V low V_{CEsat} NPN transistor

Objective specification
Supersedes data of 2002 Oct 22

2004 Aug 20

Philips
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50 V low V_{CEsat} NPN transistor PBSS4350SA

FEATURES

- Low collector-emitter saturation voltage V_{CEsat} and corresponding R_{CEsat}
- High collector current capability I_C and I_{CM}
- High collector current gain h_{FE}
- Less heat generation leading to higher efficiency.

APPLICATIONS

- Low and medium power DC/DC convertors
- Low voltage regulation (LDO)
- MOSFET drivers
- Supply line switching
- Battery chargers.

DESCRIPTION

NPN low V_{CEsat} transistor in a SOT54 plastic package.
PNP complement: PBSS5350SA.

MARKING

TYPE NUMBER	MARKING CODE
PBSS4350SA	4350SA

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V_{CEO}	collector-emitter voltage	50	V
I_C	collector current (DC)	2	A
I_{CRP}	repetitive peak collector current	3	A
R_{CEsat}	equivalent on-resistance	130	mΩ

PINNING

PIN	DESCRIPTION
1	collector
2	base
3	emitter

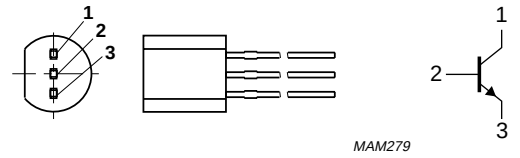


Fig.1 Simplified outline (SOT54) and symbol.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	50	V
V_{CEO}	collector-emitter voltage	open base	–	50	V
V_{EBO}	emitter-base voltage	open collector	–	5	V
I_C	collector current (DC)		–	2	A
I_{CRP}	repetitive peak collector current	note 1	–	3	A
I_{CM}	peak collector current	single peak	–	5	A
I_B	base current (DC)		–	0.5	A
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C; note 2	–	830	mW
		$T_{amb} \leq 25$ °C; note 3	–	900	mW
		$T_{amb} \leq 25$ °C; notes 1 and 2	–	1.2	W
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C
T_{amb}	operating ambient temperature		–65	+150	°C

Notes

1. Operated under pulsed conditions: pulse width $t_p \leq 100$ ms; duty cycle $\delta \leq 0.25$.
2. Device mounted on a printed-circuit board; single sided copper; tinplated; standard footprint.
3. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 1 cm^2.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j\text{-}a}$	thermal resistance from junction to ambient	in free air; notes 1 and 2	104	K/W
		in free air; note 3	121	K/W
		in free air; note 2	150	K/W

Notes

1. Operated under pulsed conditions: pulse width $t_p \leq 100$ ms; duty cycle $\delta \leq 0.25$.
2. Device mounted on a printed-circuit board; single sided copper; tinplated; standard footprint.
3. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 1 cm^2.

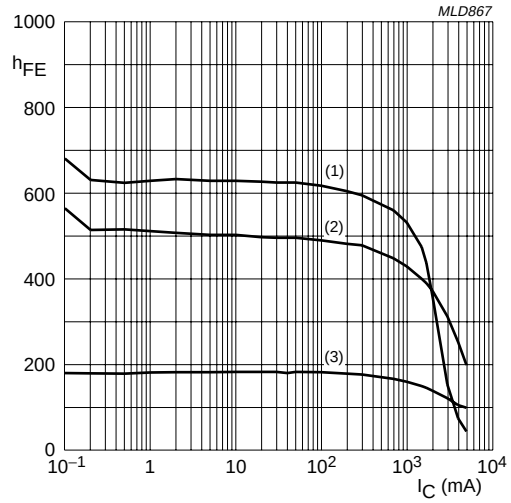
CHARACTERISTICS

T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector-base cut-off current	V_{CB} = 50 V; I_E = 0	–	–	100	nA
		V_{CB} = 50 V; I_E = 0; T_j = 150 °C	–	–	50	μA
I_{EBO}	emitter-base cut-off current	V_{EB} = 5 V; I_C = 0	–	–	100	nA
h_{FE}	DC current gain	V_{CE} = 2 V; I_C = 100 mA	300	–	–	
		V_{CE} = 2 V; I_C = 500 mA	300	–	–	
		V_{CE} = 2 V; I_C = 1 A; note 1	300	–	–	
		V_{CE} = 2 V; I_C = 2 A; note 1	200	–	–	
		V_{CE} = 2 V; I_C = 3 A; note 1	100	–	–	
V_{CEsat}	collector-emitter saturation voltage	I_C = 500 mA; I_B = 50 mA	–	–	80	mV
		I_C = 1 A; I_B = 50 mA	–	–	160	mV
		I_C = 2 A; I_B = 100 mA; note 1	–	–	280	mV
		I_C = 2 A; I_B = 200 mA; note 1	–	–	260	mV
		I_C = 3 A; I_B = 300 mA; note 1	–	–	370	mV
R_{CEsat}	equivalent on-resistance	I_C = 2 A; I_B = 200 mA; note 1	–	100	130	mΩ
V_{BEsat}	base-emitter saturation voltage	I_C = 2 A; I_B = 100 mA; note 1	–	–	1.1	V
		I_C = 3 A; I_B = 300 mA; note 1	–	–	1.2	V
V_{BEon}	base-emitter turn-on voltage	V_{CE} = 2 V; I_C = 1 A; note 1	–	–	1.2	V
f_T	transition frequency	I_C = 100 mA; V_{CE} = 5 V; f = 100 MHz	100	–	–	MHz
C_c	collector capacitance	V_{CB} = 10 V; I_E = I_e = 0; f = 1 MHz	–	–	25	pF

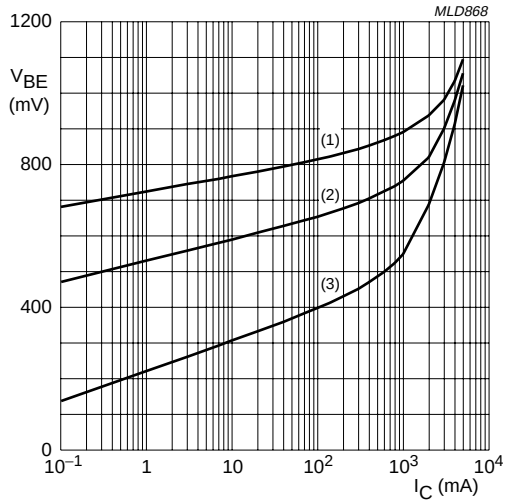
Note

1. Pulse test: $t_p \leq 300$ μs; $\delta \leq 0.02$.



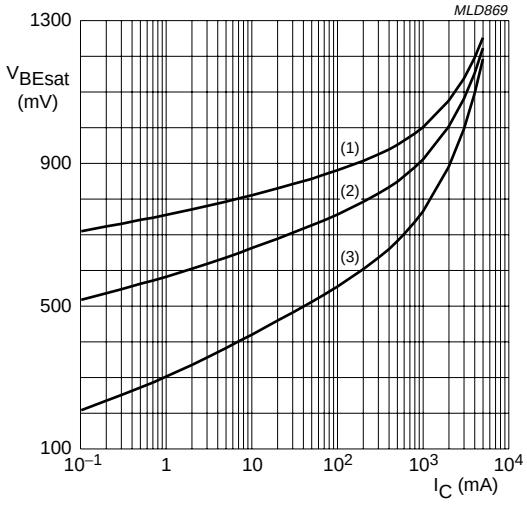
V_{CE} = 2 V.
(1) T_{amb} = 150 °C.
(2) T_{amb} = 25 °C.
(3) T_{amb} = –55 °C.

Fig.2 DC current gain as a function of collector current; typical values.



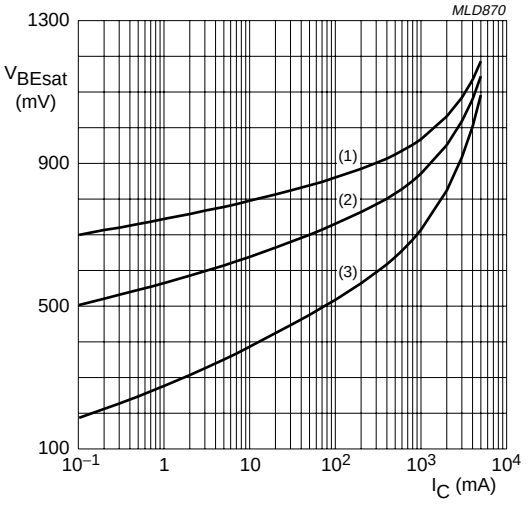
V_{CE} = 2 V.
(1) T_{amb} = –55 °C.
(2) T_{amb} = 25 °C.
(3) T_{amb} = 150 °C.

Fig.3 Base-emitter voltage as a function of collector current; typical values.



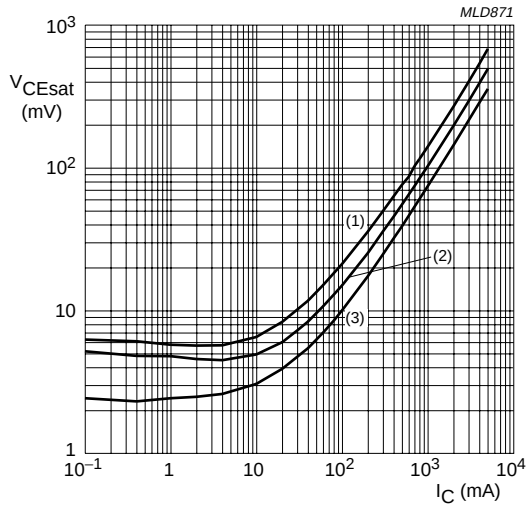
I_C/I_B = 10.
(1) T_{amb} = –55 °C.
(2) T_{amb} = 25 °C.
(3) T_{amb} = 150 °C.

Fig.4 Base-emitter saturation voltage as a function of collector current; typical values.



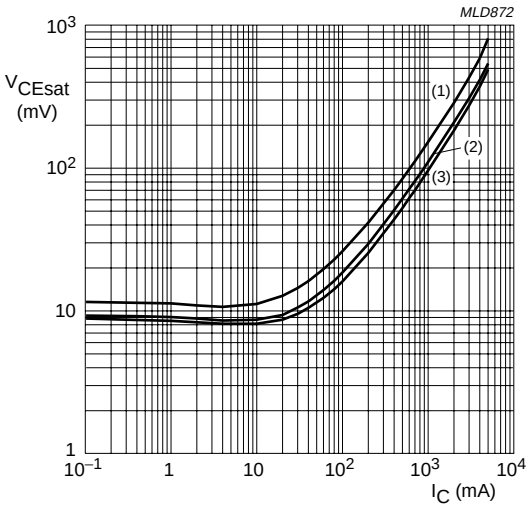
I_C/I_B = 20.
(1) T_{amb} = –55 °C.
(2) T_{amb} = 25 °C.
(3) T_{amb} = 150 °C.

Fig.5 Base-emitter saturation voltage as a function of collector current; typical values.



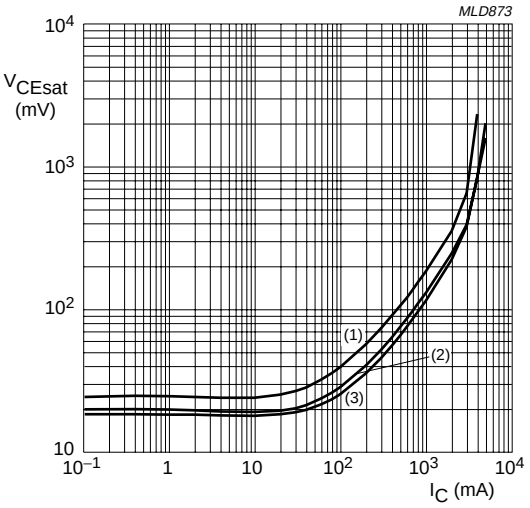
I_C/I_B = 10.
(1) T_{amb} = 150 °C.
(2) T_{amb} = 25 °C.
(3) T_{amb} = –55 °C.

Fig.6 Collector-emitter saturation voltage as a function of collector current; typical values.



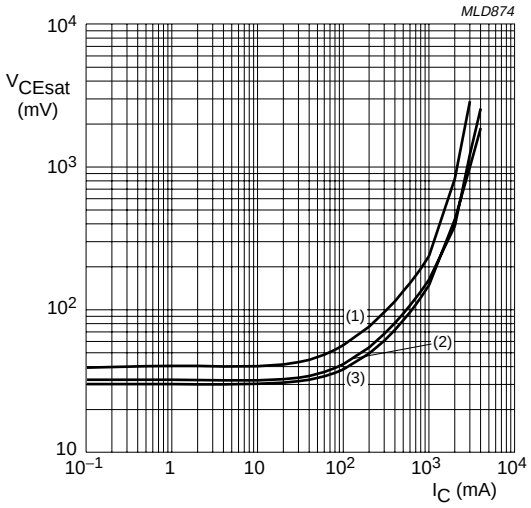
I_C/I_B = 20.
(1) T_{amb} = 150 °C.
(2) T_{amb} = 25 °C.
(3) T_{amb} = –55 °C.

Fig.7 Collector-emitter saturation voltage as a function of collector current; typical values.



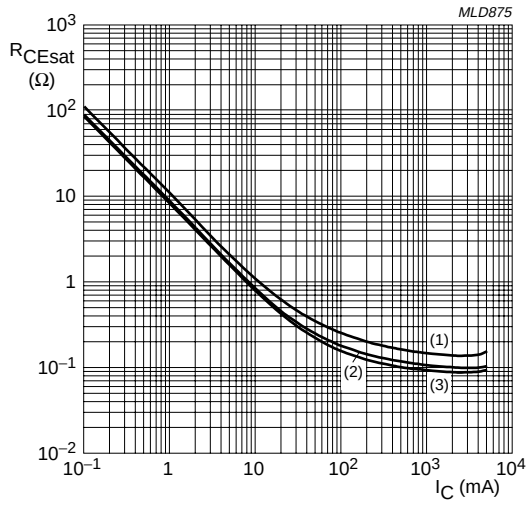
I_C/I_B = 50.
(1) T_{amb} = 150 °C.
(2) T_{amb} = 25 °C.
(3) T_{amb} = –55 °C.

Fig.8 Collector-emitter saturation voltage as a function of collector current; typical values.



I_C/I_B = 100.
(1) T_{amb} = 150 °C.
(2) T_{amb} = 25 °C.
(3) T_{amb} = –55 °C.

Fig.9 Collector-emitter saturation voltage as a function of collector current; typical values.

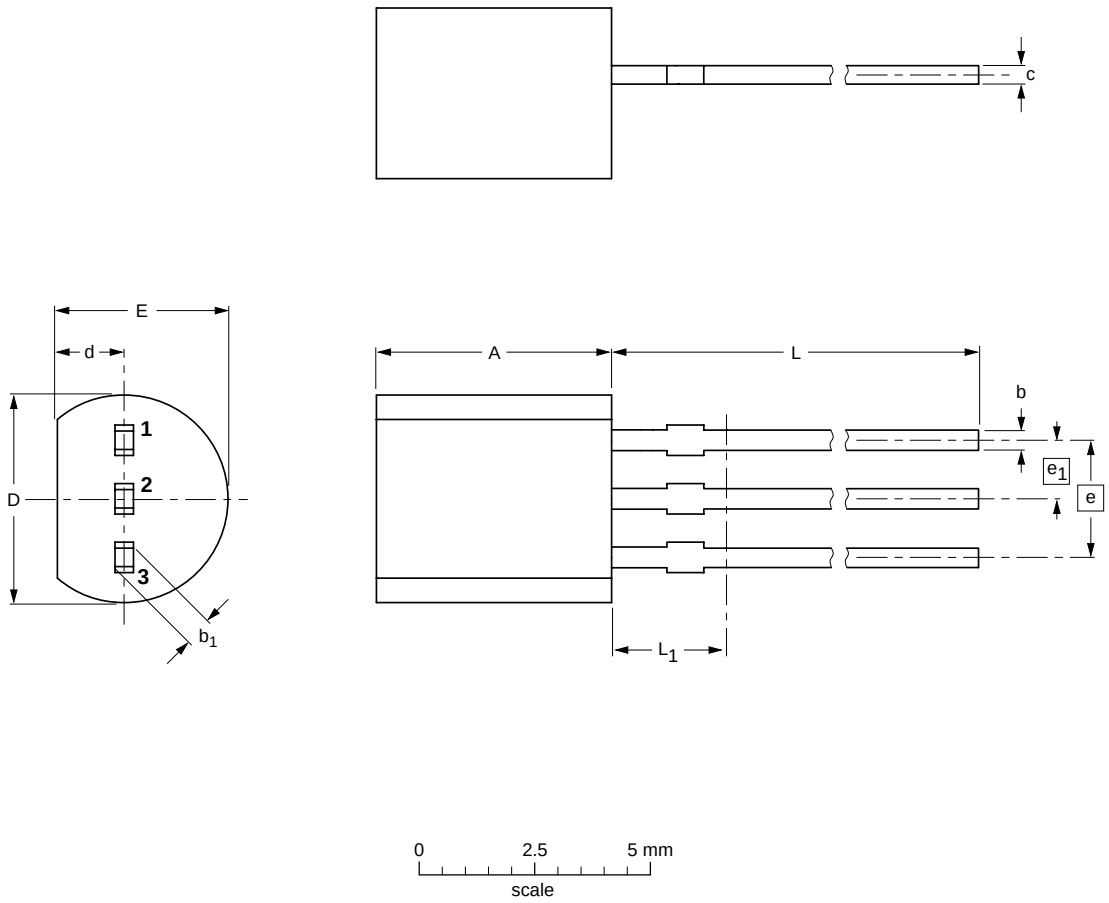


I_C/I_B = 20.
(1) T_{amb} = 150 °C.
(2) T_{amb} = 25 °C.
(3) T_{amb} = −55 °C.

Fig.10 Equivalent on-resistance as a function of collector current; typical values.

PACKAGE OUTLINE

Plastic single-ended leaded (through hole) package; 3 leads **SOT54**



DIMENSIONS (mm are the original dimensions)

UNIT	A	b	b_1	c	D	d	E	e	e_1	L	L_1 (1) max.
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5

Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT54		TO-92	SC-43A			~~97-02-28~~ 04-06-28

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS(1)	PRODUCT STATUS(2)(3)	DEFINITION
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